

3.5x2.8mm SURFACE MOUNT LED LAMP

Part Number: AAA3528SURKCGKS

Hyper Red Green

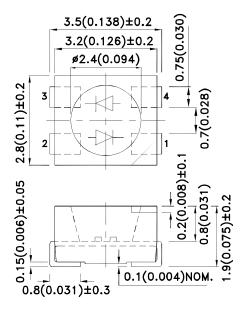
Features

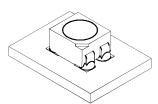
- Both chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.



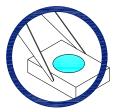
SPEC NO: DSAL0889 **REV NO: V.4A DATE: MAR/11/2015 PAGE: 1 OF 7** APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1201006793

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

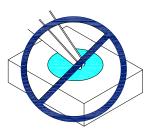
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

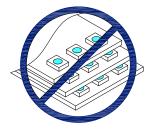


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

SPEC NO: DSAL0889 REV NO: V.4A DATE: MAR/11/2015 PAGE: 2 OF 7
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1201006793

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AAA3528SURKCGKS	Hyper Red (AlGaInP)	Water Clear	200	320	- 120°
			*55	*100	
	Green (AlGalnP)		40	80	
			*40	*80	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm	Ir=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	Ir=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	I==20mA
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	IF=20mA
lR	Reverse Current	Hyper Red Green		10 10	uA	VR = 5V

Notes:

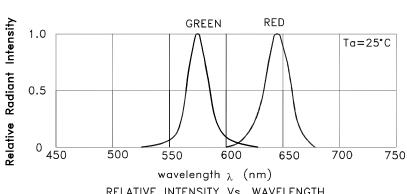
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red Green		Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

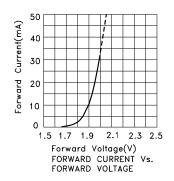
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

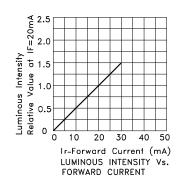
SPEC NO: DSAL0889 **REV NO: V.4A DATE: MAR/11/2015** PAGE: 3 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: L.Q.Xie ERP: 1201006793

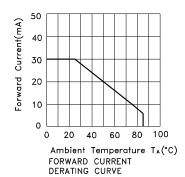


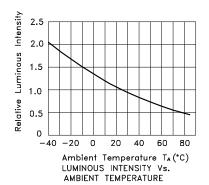
RELATIVE INTENSITY Vs. WAVELENGTH

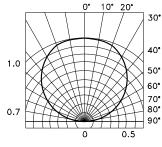
AAA3528SURKCGKS Hyper Red







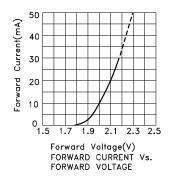


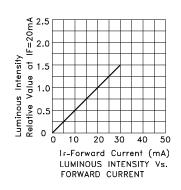


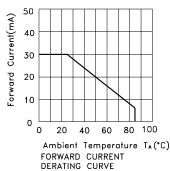
SPATIAL DISTRIBUTION

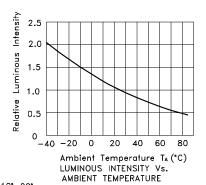
SPEC NO: DSAL0889 **REV NO: V.4A** DATE: MAR/11/2015 PAGE: 4 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1201006793 DRAWN: L.Q.Xie

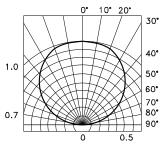
Green











SPATIAL DISTRIBUTION

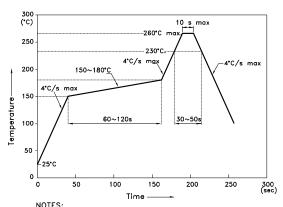
SPEC NO: DSAL0889 REV NO: V.4A DATE: MAR/11/2015 PAGE: 5 OF 7

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie ERP: 1201006793

AAA3528SURKCGKS

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - to high temperature.

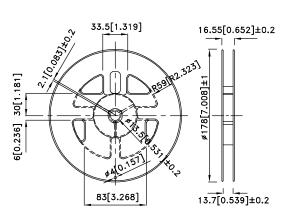
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

2.8

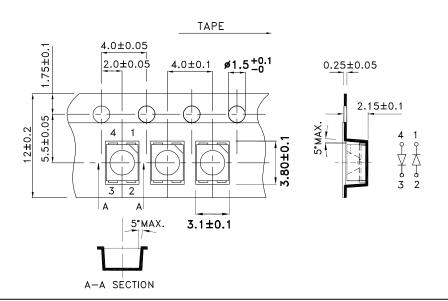
Tape Dimensions (Units : mm)

Reel Dimension



PAGE: 6 OF 7

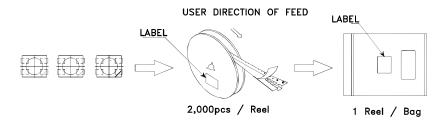
ERP: 1201006793

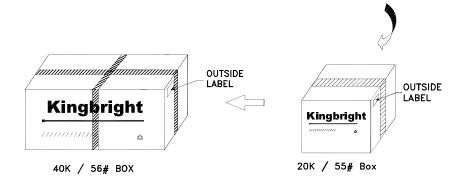


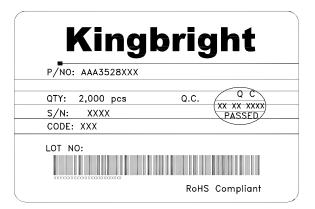
SPEC NO: DSAL0889 REV NO: V.4A DATE: MAR/11/2015
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: L.Q.Xie

PACKING & LABEL SPECIFICATIONS

AAA3528SURKCGKS







Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6. All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

 SPEC NO: DSAL0889
 REV NO: V.4A
 DATE: MAR/11/2015
 PAGE: 7 OF 7

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: L.Q.Xie
 ERP: 1201006793

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Kingbright:

AAA3528SURKCGKS